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NOMENCLATURE

c_p	specific heat, J. kg ⁻¹ . K ⁻¹
\dot{m}	mass flow rate of the cooling water, kg. m ⁻³
Q	heat transfer rate, W
R	thermal resistance, K. W ⁻¹
T _{C1} , T _{C2}	inlet and outlet temperatures from condenser section, K
T _{E1} , T _{E2}	inlet and outlet temperatures from evaporator section, K
T _S	vapor temperature, K

Subscripts

nf	nanofluid
w	water